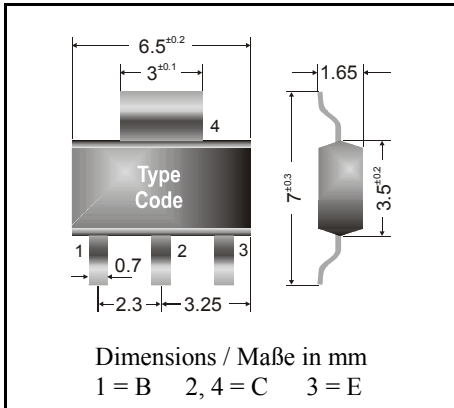


PNP

Surface mount Si-Epitaxial Planar Transistors
Si-Epitaxial Planar Transistoren für die Oberflächenmontage

PNP



Power dissipation – Verlustleistung 1.3 W
 Plastic case SOT-223
 Kunststoffgehäuse
 Weight approx. – Gewicht ca. 0.04 g
 Plastic material has UL classification 94V-0
 Gehäusematerial UL94V-0 klassifiziert
 Standard packaging taped and reeled
 Standard Lieferform gegurtet auf Rolle

Maximum ratings (T_A = 25°C)

Grenzwerte (T_A = 25°C)

| | | | BSP 30 BSP 31 | BSP 32 BSP 33 |
|---|--------|--------------------|--------------------------|--------------------------|
| Collector-Emitter-voltage | B open | - V _{CE0} | 60 V | 80 V |
| Collector-Base-voltage | E open | - V _{CB0} | 70 V | 90 V |
| Emitter-Base-voltage | C open | - V _{EB0} | 5 V | |
| Power dissipation – Verlustleistung | | P _{tot} | 1.3 W ¹⁾ | |
| Collector current – Kollektorstrom (dc) | | - I _C | 1 A | |
| Peak Collector current – Koll.-Spitzenstrom | | - I _{CM} | 2 A | |
| Peak Base current – Basis-Spitzenstrom | | - I _{BM} | 200 mA | |
| Junction temp. – Sperrschichttemperatur | | T _j | 150°C | |
| Storage temperature – Lagerungstemperatur | | T _S | - 65...+ 150°C | |

Characteristics (T_j = 25°C)

Kennwerte (T_j = 25°C)

| | | Min. | Typ. | Max. |
|--|----------------------|-------------|-------------|-------------|
| Collector-Base cutoff current – Kollektorreststrom | | | | |
| I _E = 0, - V _{CB} = 60 V | - I _{CB0} | – | – | 100 nA |
| I _E = 0, - V _{CB} = 60 V, T _j = 150°C | - I _{CB0} | – | – | 50 µA |
| Emitter-Base cutoff current – Emittorreststrom | | | | |
| I _C = 0, - V _{EB} = 5 V | - I _{EB0} | – | – | 100 nA |
| Collector saturation volt. – Kollektor-Sättigungssp. ²⁾ | | | | |
| - I _C = 150 mA, - I _B = 15 mA | - V _{CEsat} | – | – | 250 mV |
| - I _C = 500 mA, - I _B = 50 mA | - V _{CEsat} | – | – | 500 mV |

¹⁾ Mounted on P.C. board with 3 mm² copper pad at each terminal
 Montage auf Leiterplatte mit 3 mm² Kupferbelag (Löt-pad) an jedem Anschluß

²⁾ Tested with pulses t_p = 300 µs, duty cycle ≤ 2% – Gemessen mit Impulsen t_p = 300 µs, Schaltverhältnis ≤ 2%

Characteristics ($T_j = 25^\circ\text{C}$)Kennwerte ($T_j = 25^\circ\text{C}$)

| | | Min. | Typ. | Max. |
|--|--------------------|--------------------------------|--------|----------------------|
| Base saturation voltage – Basis-Sättigungsspannung ¹⁾ | | | | |
| - $I_C = 150\text{ mA}$, - $I_B = 15\text{ mA}$ | - V_{BEsat} | – | – | 1 V |
| - $I_C = 500\text{ mA}$, - $I_B = 50\text{ mA}$ | - V_{BEsat} | – | – | 1.2 V |
| DC current gain – Kollektor-Basis-Stromverhältnis ¹⁾ | | | | |
| - $V_{CE} = 5\text{ V}$, - $I_C = 100\text{ }\mu\text{A}$ | BSP 30 h_{FE} | 10 | – | – |
| - $V_{CE} = 5\text{ V}$, - $I_C = 100\text{ mA}$ | BSP 32 h_{FE} | 40 | – | 120 |
| - $V_{CE} = 5\text{ V}$, - $I_C = 500\text{ mA}$ | h_{FE} | 30 | – | – |
| - $V_{CE} = 5\text{ V}$, - $I_C = 100\text{ }\mu\text{A}$ | BSP 31 h_{FE} | 30 | – | – |
| - $V_{CE} = 5\text{ V}$, - $I_C = 100\text{ mA}$ | BSP 33 h_{FE} | 100 | – | 300 |
| - $V_{CE} = 5\text{ V}$, - $I_C = 500\text{ mA}$ | h_{FE} | 50 | – | – |
| Gain-Bandwidth Product – Transitfrequenz | | | | |
| - $V_{CE} = 5\text{ V}$, - $I_C = 10\text{ mA}$, $f = 100\text{ MHz}$ | f_T | 100 MHz | – | – |
| Collector-Base Capacitance – Kollektor-Basis-Kapazität | | | | |
| - $V_{CB} = 10\text{ V}$, $I_E = i_c = 0$, $f = 1\text{ MHz}$ | C_{CB0} | – | 20 pF | – |
| Emitter-Base Capacitance – Emitter-Basis-Kapazität | | | | |
| - $V_{EB} = 0.5\text{ V}$, $I_C = i_c = 0$, $f = 1\text{ MHz}$ | C_{EB0} | – | 120 pF | – |
| Switching times – Schaltzeiten | | | | |
| turn-on time - $I_{Con} = 100\text{ mA}$, | t_{on} | – | – | 500 ns |
| turn-off time - $I_{Bon} = 5\text{ mA}$, $I_{Boff} = 5\text{ mA}$ | t_{off} | – | – | 600 ns |
| Thermal resistance – Wärmewiderstand | | | | |
| junction to ambient air – Sperrschicht zu umgebender Luft | R_{thA} | | | 93 K/W ²⁾ |
| junction to soldering point – Sperrschicht zu Lötpad | R_{thS} | | | 12 K/W |
| Recommended complementary NPN transistors Empfohlene komplementäre NPN-Transistoren | | BSP 40, BSP 41, BSP 42, BSP 43 | | |

¹⁾ Tested with pulses $t_p = 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300\text{ }\mu\text{s}$, Schaltverhältnis $\leq 2\%$

²⁾ Mounted on P.C. board with 3 mm^2 copper pad at each terminal
Montage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluß